

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A power module, comprising:

~~a heat radiating member including member, one surface of the heat radiating member being~~ a circuit arrangement surface having a circuit arrangement ~~region; region, the circuit arrangement region being a predetermined region of the circuit arrangement surface of the heat radiating member;~~

a power circuit section including at least one electronic ~~part~~ part, ~~the entire power circuit section being and arranged in the circuit arrangement region; region of the circuit arrangement surface of the heat radiating member;~~

a wall member formed surrounding the circuit arrangement ~~region; region, the wall member and the heat radiating member forming a unitary space, the heat radiating member being a bottom of the space, for accepting a waterproofing resin, and the wall member comprising a groove in an edge facing the heat radiating member;~~

a seal member disposed in the groove such that the seal member temporarily prevents the waterproofing resin from being leaked from the surrounding wall; and

a resin layer disposed in ~~a~~ the space defined by the wall member and the heat radiating ~~member; and member,~~

~~_____ a seal member surrounding the circuit arrangement region, wherein:~~

wherein the electronic part has a plurality of leg ~~portions; portions, and~~

~~_____ the resin layer seals at least the leg~~ portions; portions. ~~and~~

~~_____ the seal member is interposed between the wall member and the heat radiating member.~~

2. (Canceled)

3. (Original) The power module according to claim 1, wherein:
the power circuit section includes at least one bus bar;
the wall member includes a hood; and
an end portion of the bus bar is inserted into the hood.
4. (Original) The power module according to claim 3, wherein:
the wall member further includes a through hole communicating a side of the
heat radiating member and a side of the hood; and
a part of the bus bar passes through the through hole.
5. (Original) The power module according to claim 4, wherein:
the wall member further includes:
a recess portion; and
another through hole communicating the side of the heat radiating
member and the recess portion.
6. (Original) The power module according to claim 3, wherein:
the bus bar has:
a first portion extending in parallel with the circuit arrangement
surface; and
a second portion standing up from the circuit arrangement surface and
inserted into the hood.
7. (Original) The power module according to claim 3, wherein:
the wall member defines a second groove;
the bus bar has:
a first portion extending in parallel with the circuit arrangement
surface;
a second portion standing up from the circuit arrangement surface; and

a third portion extending through the second groove.

8. (Original) The power module according to claim 3, wherein the bus bar protrudes from at least one of side edges of the power circuit section in outward directions.
9. (Original) The power module according to claim 1, further comprising:
an insulating layer disposed between the heat radiating member and the power circuit section.
10. (Original) The power module according to claim 9, wherein the insulating layer is thermally connected with the heat radiating member and the power circuit section.
11. (Original) The power module according to claim 1, further comprising:
a lid attached to the wall member to cover the power circuit section.
12. (Original) The power module according to claim 1, further comprising a bus bar constitution plate including a plurality of bus bars, wherein:
the electronic part is electrically connected to the power circuit section and at least one of the bus bars.
13. (Currently Amended) A method for waterproofing a power circuit section, comprising:
arranging ~~the~~ a power circuit section including at least one electronic part having a plurality of leg portions in entirely within a circuit arrangement region on a circuit arrangement surface of a heat radiating ~~member;~~ member, the circuit arrangement surface being one surface of the heat radiating member and the circuit arrangement region being a predetermined region of the circuit arrangement surface;
attaching a wall member, which is made of an insulating material and includes a groove in which a seal member is disposed at an end surface on a side of the heat radiating member, to the heat radiating member in a state where the wall member surrounds the circuit arrangement region and the seal member is closely contacted with the circuit arrangement

surface; surface of the heat radiating member to temporarily prevent a waterproofing resin from being leaked from the surrounding wall, the wall member and the heat radiating member forming a unitary space, the heat radiating member being a bottom of the space, for accepting the waterproofing resin

pouring a liquid ~~the waterproofing resin into a~~ the space formed ~~surrounded by~~ the wall member and the heat radiating member until at least the leg portions of the electronic part are sealed; and

curing the resin to form a waterproof layer.

14. (Canceled)

15. (Original) The method according to claim 14, wherein the seal member is a foam rubber.

16. (Original) The method according to claim 13, wherein the resin is a silicone resin.

17. (Original) The method according to claim 13, further comprising:
attaching a lid to an opening portion of the wall member to cover the opening portion, wherein the opening portion is formed on an opposite side of the wall member to the heat radiating member.

18. (Original) The method according to claim 13, wherein:
the power circuit section includes:
a bus bar constitution plate on which a plurality of bus bars are arranged in a predetermined pattern;
an electronic part disposed on the bus bar constitution plate; and
a control circuit board for controlling a switching operation of the electronic part, the control circuit board bonded to one surface of the bus bar constitution plate;

the electronic part is mounted to the bus bar constitution plate and the control circuit board; and

in the pouring step, the resin is poured until the bus bar constitution plate and the control circuit board are sealed.

19. (Currently Amended) A method for waterproofing a power circuit section, comprising:

fitting a seal member into a groove portion of a cylindrical wall member tightly;

attaching ~~the~~ a power circuit section to the wall member;

coating an adhesive agent on a circuit arrangement region of a heat radiating member, the circuit arrangement region being a predetermined region of a circuit arrangement surface which is one surface of the heat radiating member;

attaching the heat radiating member to the wall member so that the wall member surrounds the circuit arrangement ~~region~~ region, the wall member and the heat radiating member forming a unitary space, the heat radiating member being a bottom of the space, for accepting waterproofing resin, and the seal member in a groove in the wall member facing the heat radiating member and ~~closely contacts~~ contacting with the heat radiating member, to attach the power circuit section entirely to the circuit arrangement region;

~~pouring a liquid~~ the waterproofing resin into a the space defined-formed by the heat radiating member and the wall member; and

curing the resin to form a waterproof layer.

20. (Original) The method according to claim 19, further comprising:

attaching a lid to an opening portion of the wall member to cover the opening portion, wherein the opening portion is formed on an opposite side of the wall member to the heat radiating member.